修订记录 / Revised record

A	2018-3				
B	2021-2-18	7			

S3AC~S3MC

Rev.B Feb.-2021

DATA SHEET

描述 / Descriptions

50V~1000V 3.0A SMC

Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage 50 to1000V,Forward Current:3.0A ,SMC thin package.

特征 / Features

RoHS 2011/65/EU

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

用途 / Applications

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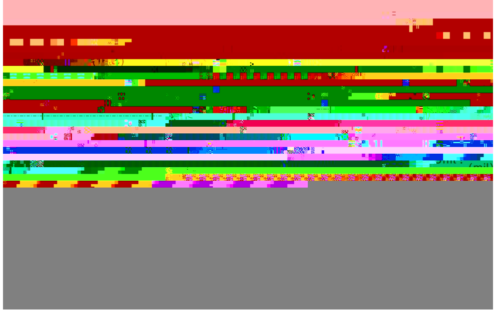
General purpose.

内部等效电路 / Equivalent Circuit

引脚排列 / Pinning

The recommended mounting pad size



印章代码 / Marking

See Marking Instructions.

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35							

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

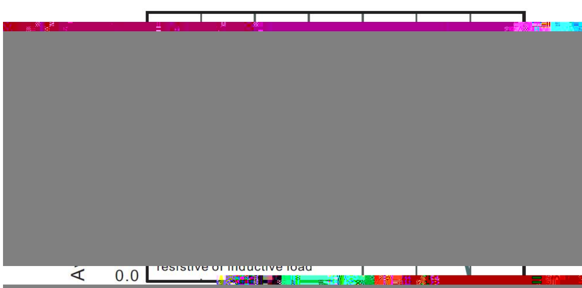
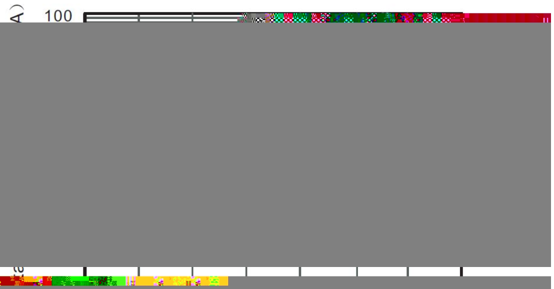
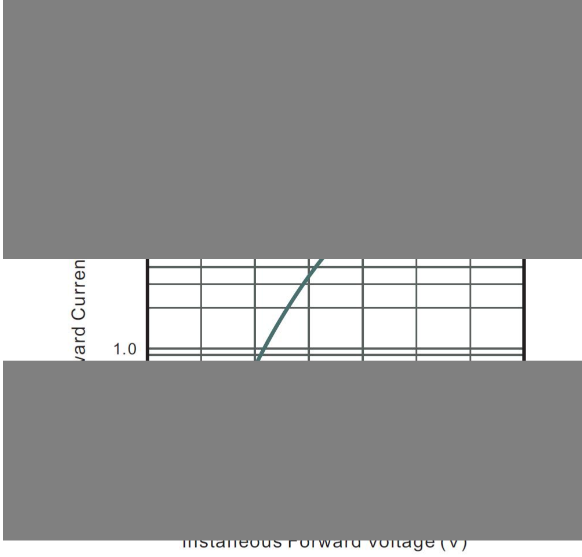


Fig.2 Typical Reverse Characteristics





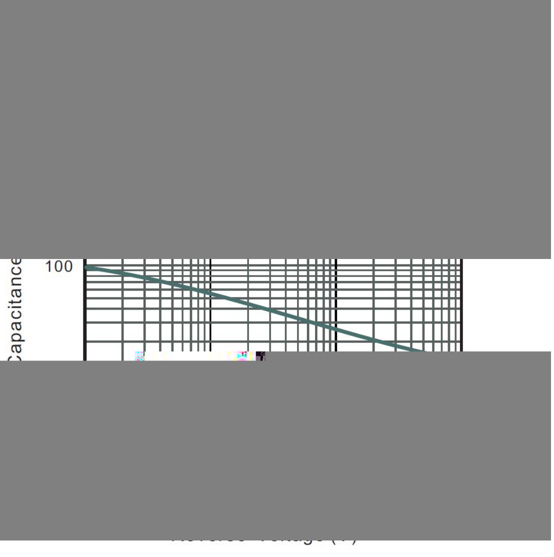
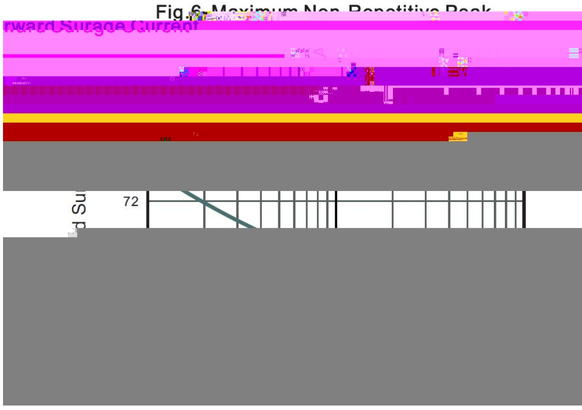
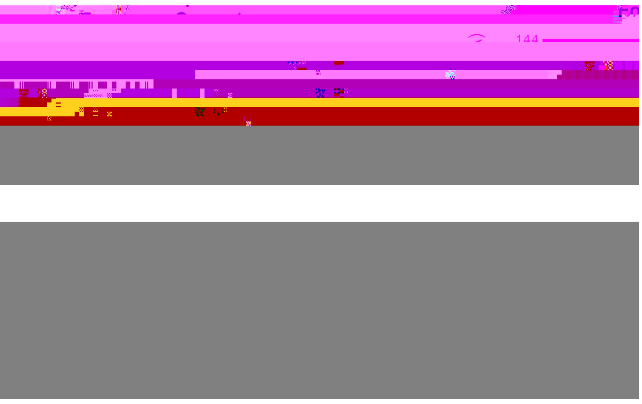


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current





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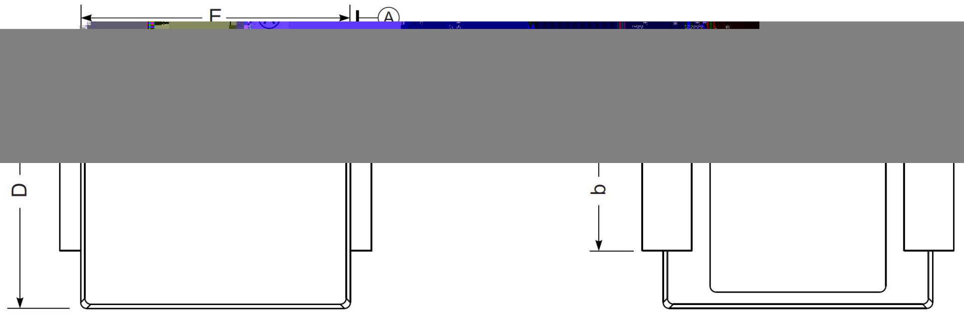
外形尺寸图 / Package Dimensions

SMC



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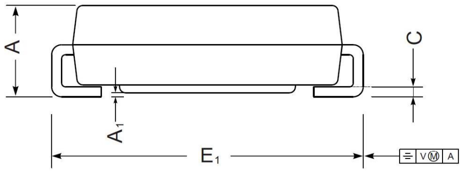

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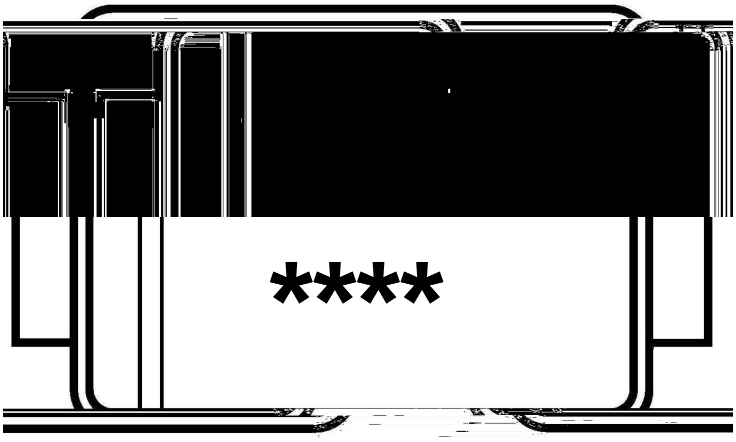
印章说明 / Marking Instructions

Marking

印章说明 / Marking Instructions



说明：

S3A： 为型号代码

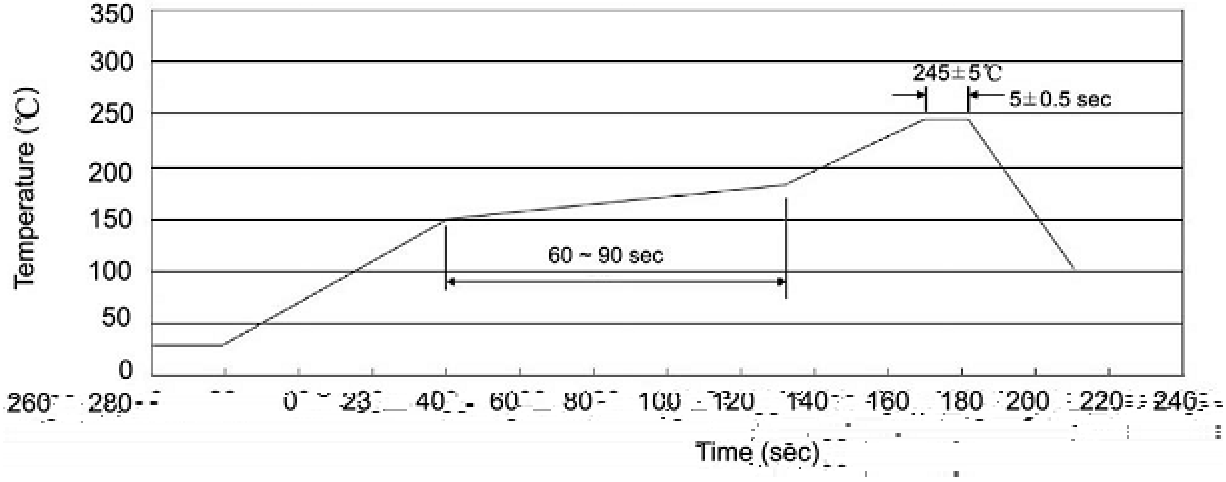
******** ： 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

Note:

S3A： Product Type Code

********： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;	1.Preheating:25~150℃, Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3 2 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5℃ 10±1 sec. Temp.:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMC	3000	2	6000	6	36000	13″ ×16	337X337X49	380X335X366

使用说明 / Notices